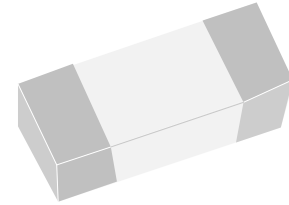


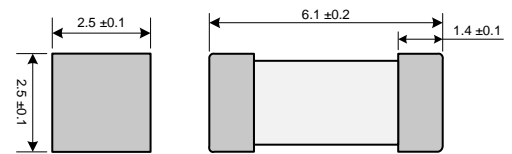
**Time Delay SMD Fuses 2410BC-G Series**
**Descriptions**

Chip Fuse devices are set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.

2410BC-G SMD fuses for the small size and good electrical performance, reliability and quality.


**Top View (2410BC-G)**

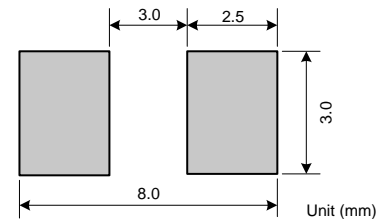
Electrical Characteristics			
Rated Current	1.0In	2.0In	3.5In
1A-10A	4 hour min	120 sec max	10 msec min

**Product Dimensions**


Unit (mm)

**Features**

- Designed to UL 248-14
- 250Vac for lighting application
- Compatible with reflow and wave soldering
- One time positive disconnect
- RoHS compliant

**Recommended land pattern**


Unit (mm)

**Electrical information (Tamb=25°C)**

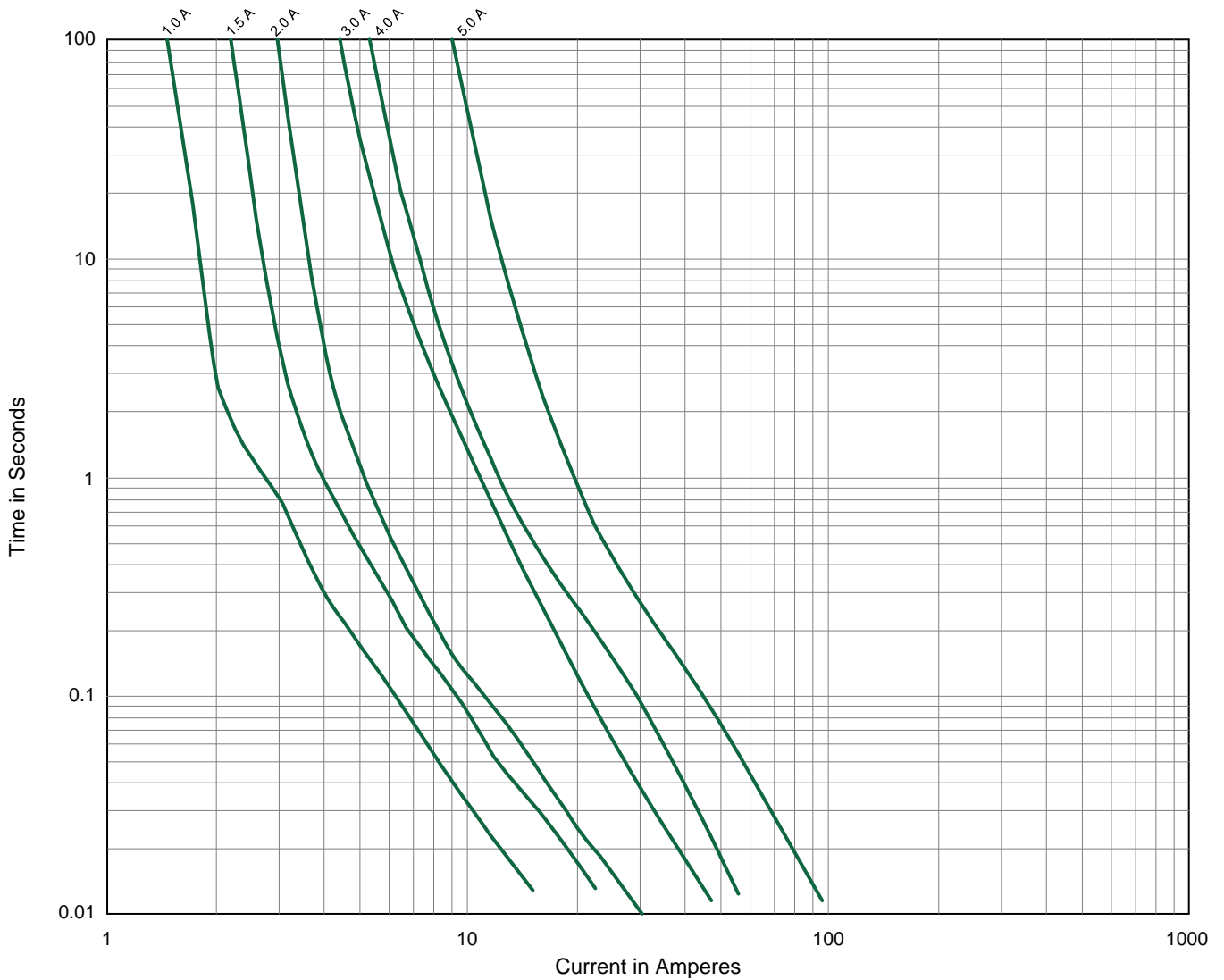
Part number	Rated Voltage	Rated Current	Breaking Capacity *	Typical Cold Resistance *	Typical Voltage Drop	Typical Pre-arcing I <sup>2</sup> t *
	AC (V)	(A)	@250V AC (A)	(mΩ)	(mV)	(A <sup>2</sup> Sec)
2410BC250-0100G	250	1.00	50	150	158	3
2410BC250-0150G	250	1.50	50	65	145	7
2410BC250-0200G	250	2.00	50	47	137	10
2410BC250-0250G	250	2.50	50	-	-	11.3
2410BC250-0300G	250	3.00	50	-	-	16
2410BC250-0350G	250	3.50	50	-	-	19
2410BC250-0400G	250	4.00	50	-	-	21
2410BC250-0500G	250	5.00	50	-	-	24
2410BC250-0600G	250	6.00	50	-	-	25.9
2410BC250-0630G	250	6.30	50	-	-	31.8
2410BC250-0700G	250	7.00	50	-	-	39.2
2410BC250-0800G	250	8.00	50	-	-	51.2
2410BC250-1000G	250	10.00	50	-	-	90

\* AC Interrupting Rating (measured at designated voltage, 100% power factor)

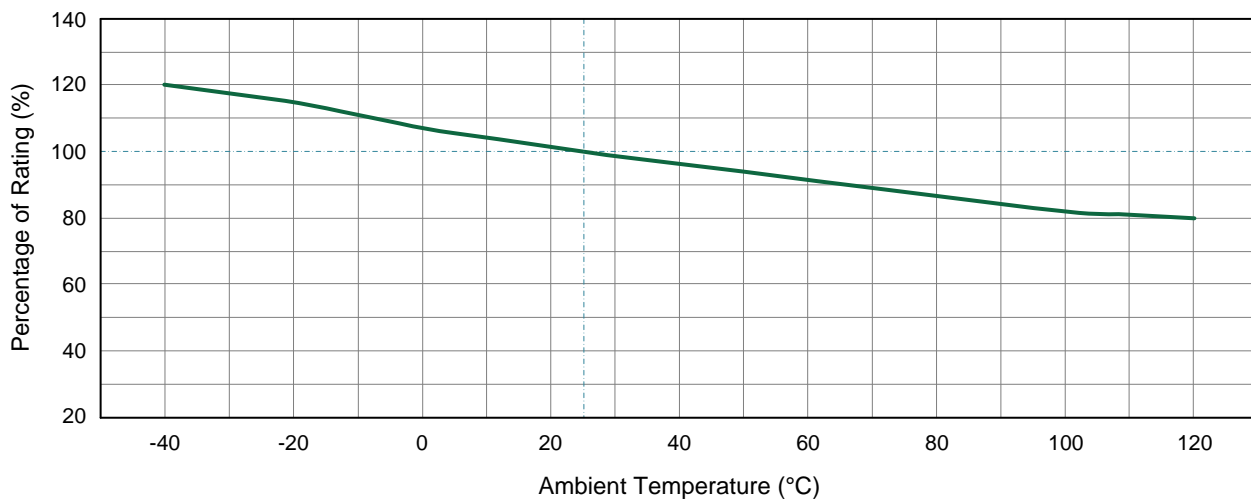
\* DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25 °C

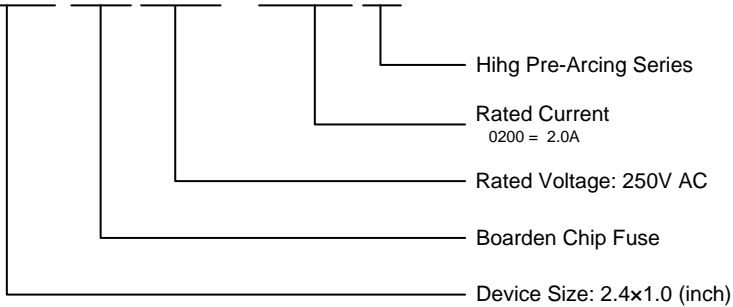
\* Typical Pre-arcing I<sup>2</sup>t are measured at 10In Current

**Time-Current Curves**



**Temperature Derating Curve**

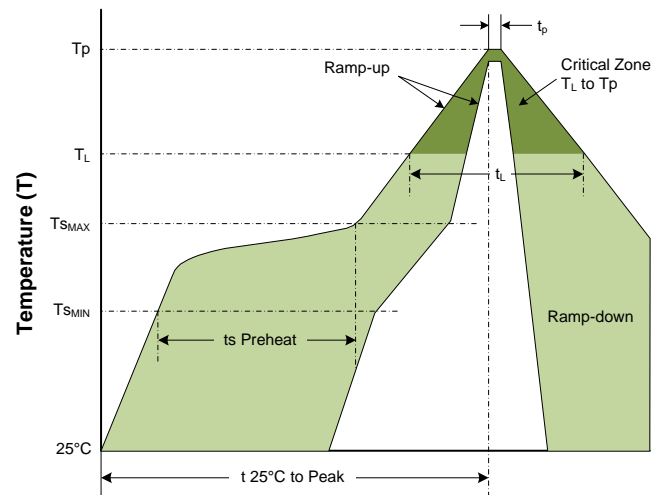


**Part Numbering System**
**2410 BC 250 - 0200 G**

**Order Information**

Device	Quantity	Reel Size
2410BC-G Series	1000 pcs	7 Inch (178.0mm)

**Soldering Parameters**

Profile Feature	Lead-Free Assembly
Average Ramp-up Rate ( $T_{S_{MAX}}$ to $T_p$ ) Average Ramp-down Rate ( $T_p$ to $T_L$ )	3°C/second max. 6°C/second max.
<b>Preheat</b> • Temperature Min ( $T_{S_{MIN}}$ ) • Temperature Max ( $T_{S_{MAX}}$ ) • Time ( $t_s$ Preheat)	150°C 200°C 60-180 seconds
<b>Time maintained above:</b> • Temperature ( $T_L$ ) • Time ( $t_L$ )	217°C 60-150 seconds
<b>Peak/Classification Temperature</b> • Temperature ( $T_p$ )	260 <sup>+0/-5</sup> °C
<b>Time within 5°C of actual Peak</b> Time ( $t_p$ )	20-40 seconds
<b>Time 25°C to peak Temperature</b>	8 minutes max
<b>Do not exceed</b>	280 °C



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